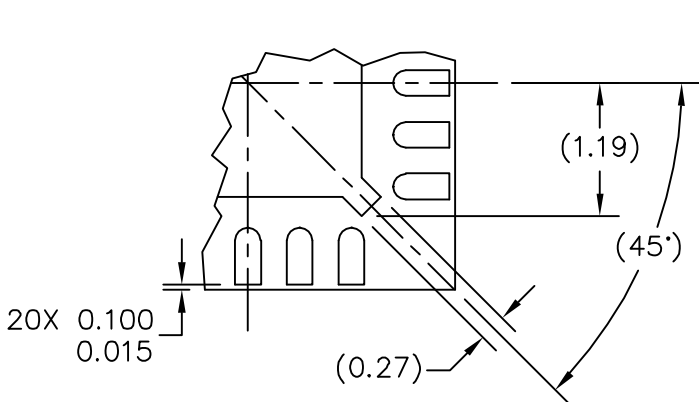
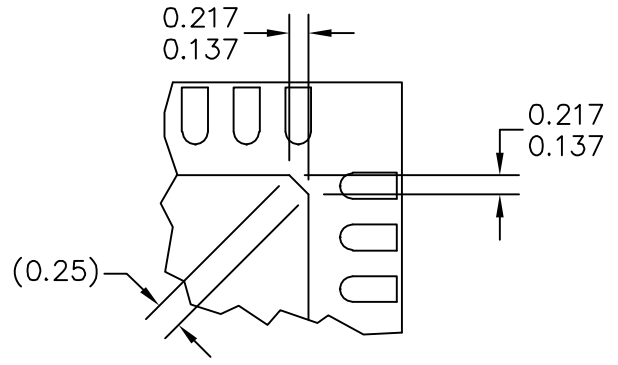


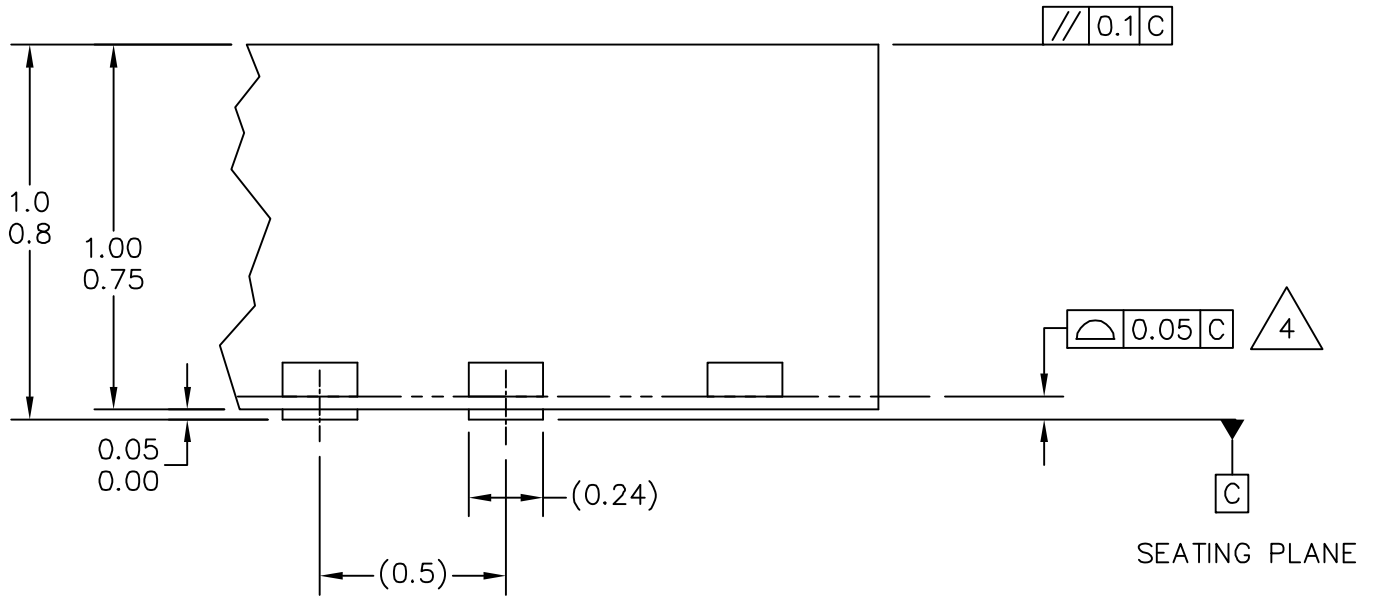
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<b>TITLE:</b> THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 20 TERMINAL, 0.5 PITCH (4 X 4 X 1)	DOCUMENT NO: 98ARH98438A	REV: E	
	CASE NUMBER: 1308-03	17 APR 2006	
	STANDARD: JEDEC MO-220 VGGD-1		



DETAIL N  
CORNER CONFIGURATION



DETAIL M  
BACKSIDE PIN 1 INDEX




DETAIL G  
VIEW ROTATED 90° CW

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFN.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. MIN. METAL GAP SHOULD BE 0.2MM.

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